SECTION II—CLAIMS

1.-13. (Canceled)

14. (Previously Presented) A process of forming a micro electromechanical (MEMS) package comprising:

providing a semiconductor device including an active surface;

providing a conveyance with at least one embedded MEMS device disposed therein; and

supporting the conveyance over the active surface using a plurality of electrical contacts in a contact array, wherein the at least one embedded MEMS device communicates electrically to the semiconductor device via at least one of the contacts in the contact array.

15. (Original) The process according to claim 14, wherein the at least one embedded MEMS device is selected from a switch, a capacitor, an inductor, an oscillator, a power supply, and combinations thereof.

16. (Original) The process according to claim 14, wherein the conveyance comprises a via disposed therein, the process further comprising:

providing at least one detached MEMS device in a first structure; and

accommodating the at least one detached MEMS device through the via, upon the active surface.

17. (Original) The process according to claim 14, wherein the conveyance comprises a via disposed therein, the process further comprising:

providing at least one detached MEMS device in a first structure;

placing the at least one detached MEMS device on the semiconductor device; and

accommodating the at least one detached MEMS device through the via, upon the active surface.

18. (Original) The process according to claim 14, wherein the conveyance comprises a via disposed therein, the process further comprising:

providing at least one detached MEMS device in a first structure;

accommodating the at least one detached MEMS device upon the active surface;

providing a sealing structure; and

disposing the sealing structure in a manner sufficient to isolate at least one of the at least one detached MEMS device.

19. (Original) The process according to claim 14 further comprising:

forming an integrated package comprising the semiconductor device and the conveyance.

20. (Original) The process according to claim 14 further comprising:

forming an integrated package comprising the semiconductor device, the conveyance, and at least one detached MEMS device in a first structure, wherein the at least one detached MEMS device is accommodated upon the semiconductor device.

21. (Original) The process according to claim 20 further comprising:

encapsulating the detached MEMS device and the conveyance to form an integrated package.

22. (Original) The process according to claim 14 further comprising:

encapsulating the semiconductor device to form an integrated package, wherein the at least one detached MEMS device is accommodated upon the semiconductor device.

23. (Previously Presented) A process comprising:

providing a semiconductor device;

accommodating a detached micro electromechanical structure (MEMS) device upon the semiconductor device;

supporting a conveyance over an active surface using a plurality of electrical contacts in a contact array, wherein the conveyance surrounds the detached MEMS device and the detached MEMS device communicates electrically to the semiconductor device via at least one of the contacts in the contact array; and

contacting encapsulation material with at least one of the semiconductor device, the detached MEMS device, and the conveyance to form an integrated MEMS package.

24. (Previously Presented) The process according to claim 23, further comprising:

embedding the detached MEMS device in the conveyance.

25. (Original) The process according to claim 23, further comprising:

providing a sealing structure; and

interposing the sealing structure upon the semiconductor device in a manner sufficient to isolate at least one of the at least one detached MEMS device.

26.-30. (Canceled)